

GooLED-VOS-4830 Pin Fin LED Heat Sink Φ48mm for Vossloh-Schwabe

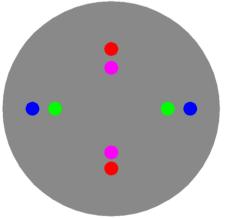
# **Features VS Benefits**

- \* The GooLED-VOS-4830 Vossloh-Schwabe Pin Fin LED Heat Sinks are specifically designed for luminaires using the Vossloh-Schwabe LED engines.
- \* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- \* For spotlight and downlight designs from 400 to 1,300 lumen.
- \* Thermal resistance range Rth 6.25°C/W.
- \* Modular design with mounting holes foreseen for direct mounting of Vossloh-Schwabe COB series.
- \* Diameter 48.0mm standard height 30.0mm Other heights on request.
- \* Forged from highly conductive aluminum.

#### Zhaga LED engine and radiator assembly is a unified future international standardization

- \* Below you find an overview of Vossloh-Schwabe COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- \* In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.





#### Vossloh-Schwabe LED Modules directly Mounting Options Vossloh-Schwabe LUGA Shop Gen. 5/ Gen.6 COB Series (13.5\*13.5): :

DMS124\*\*\*H; DMS123\*\*\*G:

With the Zhaga Book 11 holders for the green indicator marks.

AAG.STUCCHI: 8100-G2;

#### Vossloh-Schwabe LUGA Shop Gen. 5/ Gen.6 COB Series (19.0\*19.0):

DMS125\*\*\*H; DMS126\*\*\*H; DMS126\*\*\*G;

#### Vossloh-Schwabe LUGA Shop TW COB Series:

Without the holders for the red indicator marks.

Direct mounting with machine screws M3x6.5mm.





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## **Mounting Options and Drawings & Dimensions**

Example:GooLED-VOS-4830-B-1,2

Example:GooLED-VOS-48 1 - 2 - 3

1 Height (mm)

**Anodising Color** 

B-Black

C-Clear

Z-Custom

Mounting Options - see graphics for details Combinations available

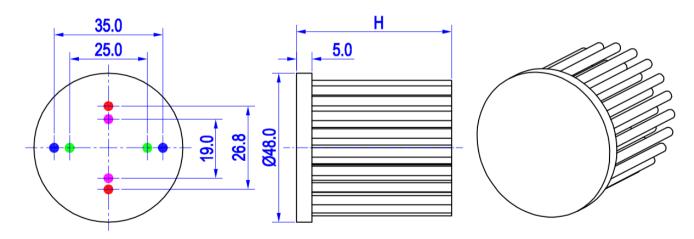
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means option 1 and 2 combined

### Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	COB series (13.5*13.5)	/	М3	6.5mm	19.0mm/ 2-@180°
2		BJB Holder 47.319.6294.50	М3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
		AAG.STUCCHI 8100-G2	МЗ	6.5mm	
3	COB series (19.0*19.0)	/			26.8mm/ 2-@180°
4		BJB Holder 47.319.2021.50			35.0mm/ 2-@180° (Zhaga book 3)
		AAG.STUCCHI 8101-G2			







## The product deta table

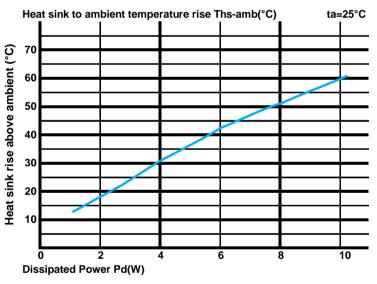


Model No.	GooLED-VOS-4830		
Heatsink Size	Ф48хH30mm		
Heatsink Material	AL1070		
Finish	Black Anodized		
Weight (g)	46.0		
Dissipated power (Ths-amb,50℃)	8.0 (W)		
Cooling surface area (mm²)	15420		
Thermal Resistance (Rhs-amb)	6.25 (°C/W)		

#### The thermal data table

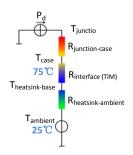
- \* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- \*To calculate the dissipated power please use the following formula:  $Pd = Pe \times (I \eta L)$ .
  - Pd Dissipated power ; Pe Electrical power ;  $\eta L = \text{Light effciency of the LED module};$

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)	
		GooLED-VOS-4830		
Dissipated Power Pd(W)	2.0	9.00	18.0	
	4.0	7.50	30.0	
	6.0	7.00	42.0	
	8.0	6.25	50.0	
	10.0	5.90	59.0	



- \*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- $\label{thm:mingFa} \mbox{MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.}$

 $Either thermal\ grease, A\ thermal\ pad\ or\ a\ phase\ change\ thermal\ pad\ thickness\ 0.\ I-0.\ I\ 5mm\ is\ recommended.$ 



- \*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula:  $\theta = (Ths Ta)/Pd$
- $\theta\,$  Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;
- \*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is  $R_{junction-case}$ , the thermal resistance of the TIM outside the package is  $R_{interface (TIM)}$  [°C/M], the thermal resistance with the heat sink is  $R_{heatsink-ambient}$  [°C/M], and the ambient temperature is  $T_{ambient}$  [°C].
- \*Thermal resistances outside the package  $R_{interface\,(TIM)}$  and  $R_{heatsink-ambient}$  can be integrated into the thermal resistance  $R_{case-ambient}$  at this point. Thus, the following formula is also used:

 $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$